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Chang et al.

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(54) **METHOD FOR FABRICATING
ELECTRONIC PACKAGE**

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Jun. 28, 2023, now Pat. No. 12,033,868, which is a
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(58) **Field of Classification Search**
CPC H01L 21/44; H01L 21/561; H01L 21/50;
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Primary Examiner — Dale E Page

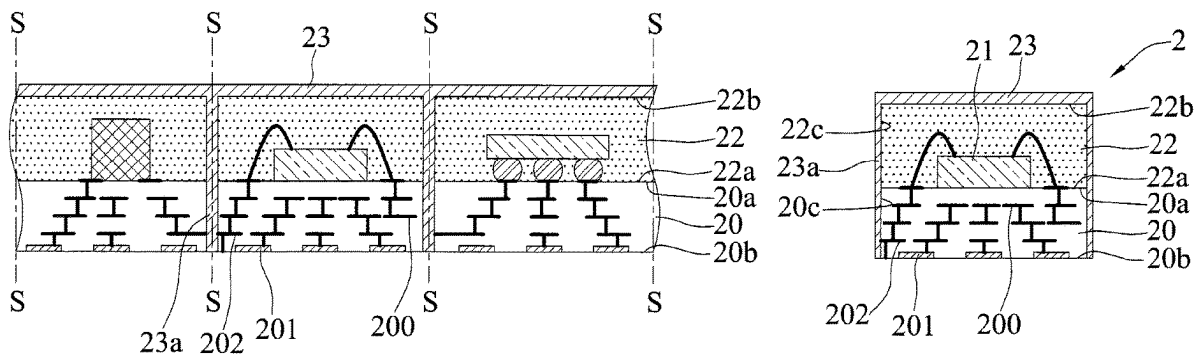
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(57) **ABSTRACT**

An electronic package and a method for fabrication the same
are provided. The method includes: disposing an electronic
component on a substrate; forming an encapsulant layer on
the substrate to encapsulate the electronic component; and
forming a shielding layer made of metal on the encapsulant
layer. The shielding layer has an extending portion extend-
ing to a lateral side of the substrate along a corner of the
encapsulant layer, without extending to a lower side of the
substrate. Therefore, the present disclosure prevents the
shielding layer from coming into contact with conductive
pads disposed on the lower side of the substrate and thereby
avoids a short circuit from occurrence.

7 Claims, 4 Drawing Sheets



Related U.S. Application Data

continuation of application No. 17/123,630, filed on Dec. 16, 2020, now Pat. No. 11,728,178, which is a division of application No. 15/628,416, filed on Jun. 20, 2017, now Pat. No. 10,903,088.

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H01L 23/485 (2006.01)
H01L 23/552 (2006.01)
H10D 30/60 (2025.01)
H10D 84/40 (2025.01)

(52) **U.S. Cl.**

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See application file for complete search history.

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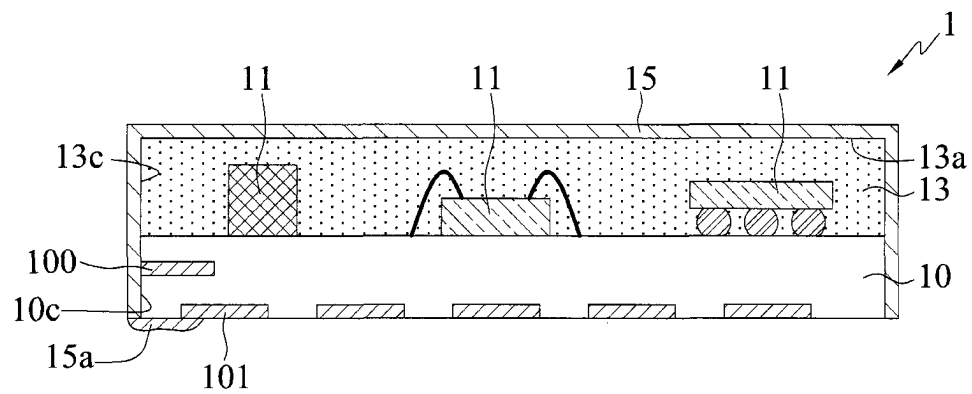


FIG. 1 (PRIOR ART)

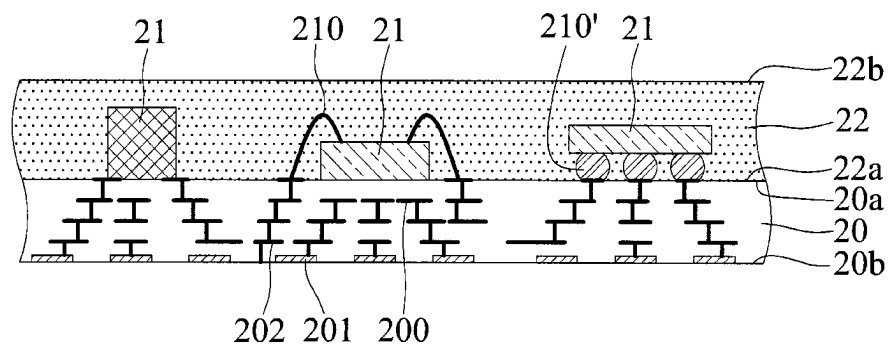


FIG. 2A

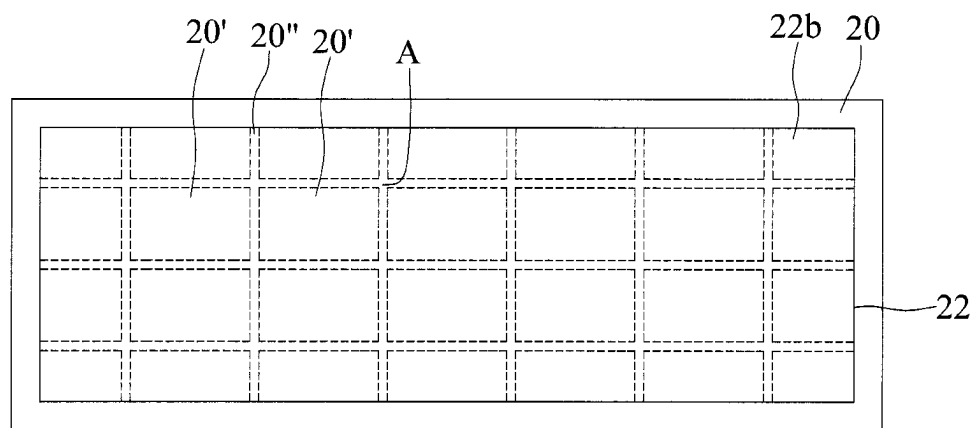


FIG. 2A'

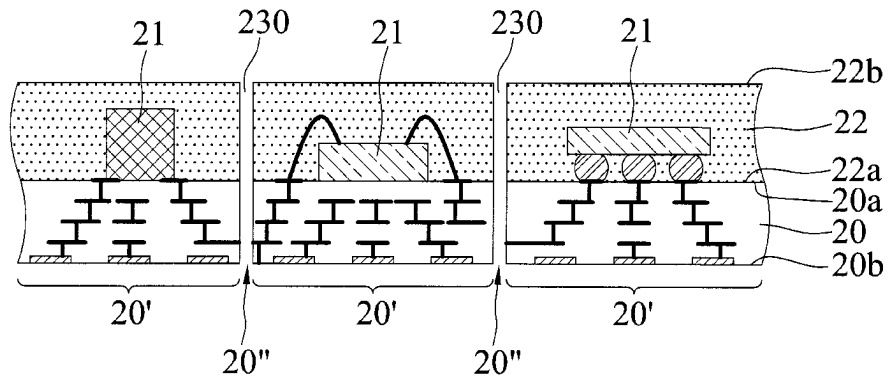


FIG. 2B

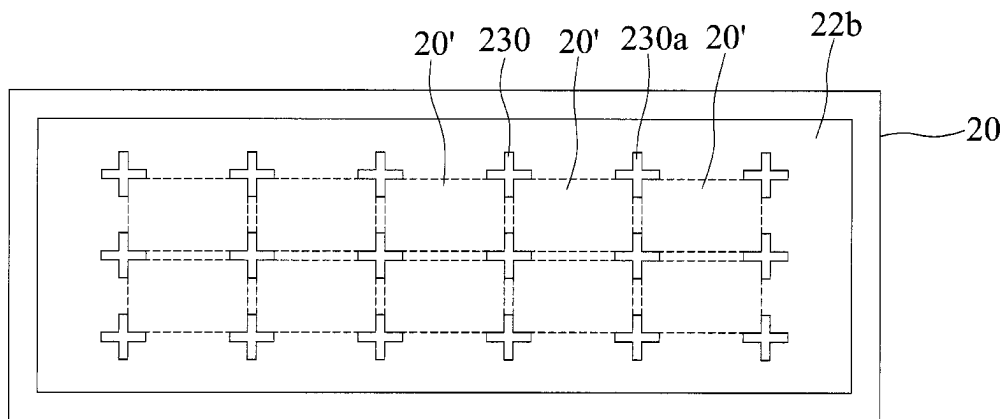


FIG. 2B'

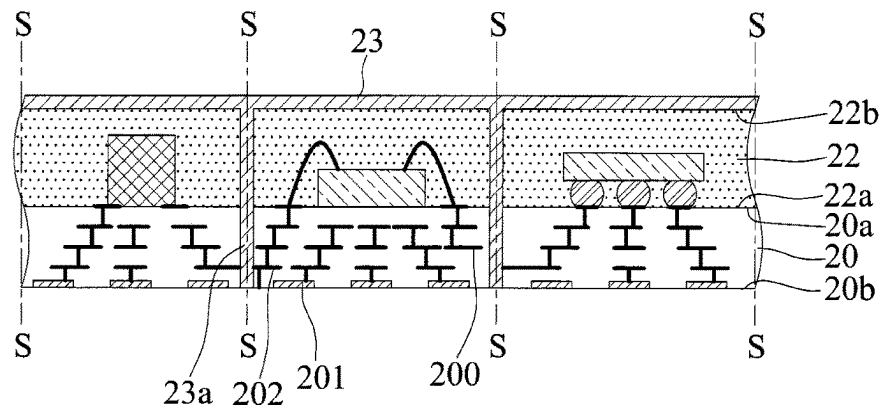


FIG. 2C

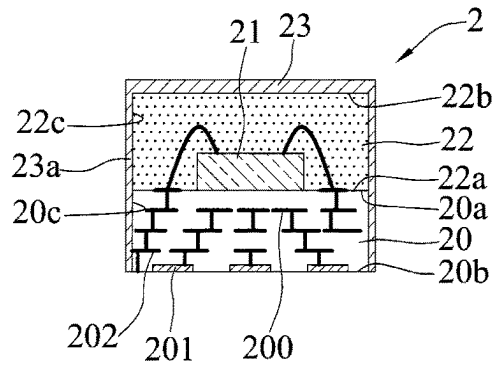


FIG. 2D

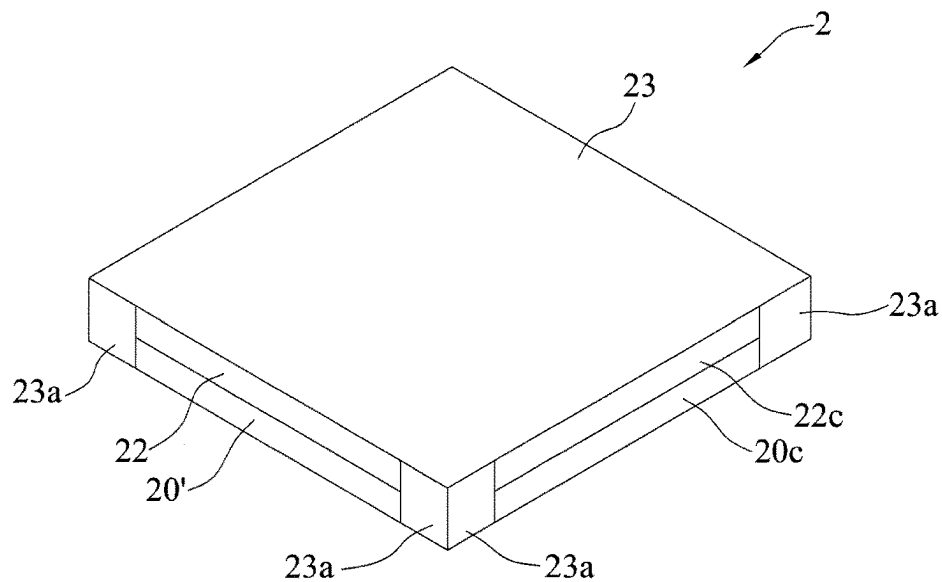


FIG. 2D'

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METHOD FOR FABRICATING ELECTRONIC PACKAGE

RELATED APPLICATIONS

This is a continuation of U.S. patent application Ser. No. 18/343,544, filed on Jun. 28, 2023, which is a continuation of U.S. patent application Ser. No. 17/123,630, filed on Dec. 16, 2020, which is a division of U.S. patent application Ser. No. 15/628,416, filed on Jun. 20, 2017, which claims foreign priority under 35 U.S.C. § 119(a) to Taiwan Application No. 106110778, filed on Mar. 30, 2017, the entire contents of all of which are incorporated herein by reference for all purposes.

BACKGROUND

1. Technical Field

The present disclosure relates to packaging technologies, and, more particularly, to a semiconductor package immune from electromagnetic interference and a method for fabricating the same.

2. Description of Related Art

Along with the progress of semiconductor technologies, various package types have been developed for semiconductor devices. To improve electrical performance, a lot of semiconductor products are provided with a shielding function so as to prevent electromagnetic interference (EMI) from occurrence.

FIG. 1 is a schematic cross-sectional view of a conventional RF module **1** having an EMI shielding function. Referring to FIG. 1, a plurality of electronic components **11** such as RF and non-RF chips are disposed on and electrically connected to a substrate **10**, and an encapsulant layer **13** made of an epoxy resin is formed on the substrate **10** and encapsulates the electronic components **11**. Further, a metal layer **15** is formed on an upper surface **13a** and a side surface **13c** of the encapsulant layer **13** and a side surface **10c** of the substrate **10** by sputtering. The metal layer **15** is electrically connected to a grounding structure **100** on the side surface **10c** of the substrate **10** so as to be further electrically connected to a system ground, thus protecting the electronic components **11** from being adversely affected by external EMI.

In addition, a plurality of conductive pads **101** are generally formed on a lower surface of the substrate **10** for mounting balls. Since the conductive pads **101** positioned around an outer periphery of the lower surface of the substrate **10** is very close to edges of the substrate **10**, during the sputtering process, the metal layer **15** easily overflows to the lower surface of the substrate **10** and comes into contact with the conductive pads **101**, thus resulting in a short circuit.

Therefore, there is a need to provide an electronic package and a method for fabricating the same so as to overcome the above-described drawbacks.

SUMMARY

In view of the above-described drawbacks, the present disclosure provides an electronic package, which comprises: a substrate having a first side, a second side opposite to the first side, and a lateral side adjacent to the first side and the second side; an electronic component disposed on the first

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side of the substrate and electrically connected to the substrate; an encapsulant layer formed on the first side of the substrate, encapsulating the electronic component, and having a first surface bonded to the first side of the substrate, a second surface opposite to the first surface, and a side surface adjacent to the first surface and the second surface; and a shielding layer formed on the second surface of the encapsulant layer and having an extending portion extending from a portion of an edge of the second surface of the encapsulant layer to the lateral side of the substrate along the side surface of the encapsulant layer, the extending portion being free from extending to the second side of the substrate, with a portion of the side surface of the encapsulant layer and a portion of the lateral side of the substrate exposed from the shielding layer.

The present disclosure further provides a method for fabricating an electronic package, which comprises: providing a substrate has a first side, a second side opposite to the first side, and a lateral side adjacent to the first side and the second side; disposing at least one electronic component on the first side of the substrate, and electrically connecting the electronic component to the substrate; forming on the substrate an encapsulant layer encapsulating the electronic component and having a first surface bonded to the first side of the substrate, a second surface opposite to the first surface, and a side surface adjacent to the first surface and the second surface; and forming on the second surface of the encapsulant layer a shielding layer having an extending portion extending from a portion of an edge of the second surface of the encapsulant layer to the lateral side of the substrate along the side surface of the encapsulant layer, the extending portion being free from extending to the second side of the substrate, with a portion of the side surface of the encapsulant layer and a portion of the lateral side of the substrate exposed from the shielding layer.

In an embodiment, the shielding layer is formed by: providing a carrier having a plurality of substrates and a plurality of isolating portions formed between the substrates; disposing a plurality of electronic components on the substrates, with the encapsulant layer encapsulating the electronic components; forming in the encapsulant layer a plurality of through holes extending to the lateral sides of the substrates and corresponding in position to the isolating portions at corners of the substrates; forming the shielding layer on the second surface of the encapsulant layer, with the shielding layer extending into the through holes to form the extending portions; and performing a singulation process along the isolating portions to separate the substrates from one another.

In an embodiment, the substrate has a plurality of conductive pads exposed from the second side of the substrate.

In an embodiment, the substrate has a grounding portion in contact with the shielding layer. In another embodiment, the grounding portion communicates with the lateral side of the substrate and is in contact with the extending portion of the shielding layer.

In an embodiment, the encapsulant layer is made of an insulating material.

In an embodiment, the shielding layer is made of a conductive material.

In an embodiment, the extending portion extends from a corner of the second surface of the encapsulant layer toward a corner of the second side of the substrate.

According to the present disclosure, the extending portion of the shielding layer extends from a portion of an edge of the second surface of the encapsulant layer to the lateral side of the substrate along the side surface of the encapsulant

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layer, the extending portion being free from extending to the second side of the substrate, with a portion of the side surface of the encapsulant layer and a portion of the lateral side of the substrate exposed from the shielding layer. As such, the present disclosure prevents the extending portion from coming into contact with the conductive pads of the substrate, thereby effectively avoiding a short circuit from occurrence.

BRIEF DESCRIPTION OF DRAWINGS

FIG. 1 is a schematic cross-sectional view of a conventional RF module;

FIGS. 2A to 2D are schematic cross-sectional views showing a method for fabricating an electronic package according to the present disclosure;

FIGS. 2A' and 2B' are schematic upper views of FIGS. 2A and 2B, respectively; and

FIG. 2D' is a schematic enlarged perspective view of FIG. 2D.

DETAILED DESCRIPTION OF EMBODIMENTS

The following illustrative embodiments are provided to illustrate the present disclosure; these and other advantages and effects can be apparent to those in the art after reading this specification. It should be noted that all the drawings are not intended to limit the present disclosure. Various modifications and variations can be made without departing from the spirit of the present disclosure. Further, terms such as "first", "second", "upper", "lower", "a" etc. are merely for illustrative purposes and should not be construed to limit the scope of the present disclosure.

FIGS. 2A to 2D are schematic cross-sectional views showing a method for fabricating an electronic package 2 according to the present disclosure.

Referring to FIG. 2A, a carrier 20 having a first side 20a and a second side 20b opposite to the first side 20a is provided, and a plurality of electronic components 21 are disposed on the first side 20a of the carrier 20. Then, an encapsulant layer 22 is formed on the first side 20a of the carrier 20 to encapsulate the electronic components 21.

In an embodiment, referring to FIG. 2A', the carrier 20 is of a full-panel type, which has a plurality of substrates 20' arranged in an array and a plurality of isolating portions 20'' formed between the substrates 20'. In an embodiment, each of the substrates 20' is a circuit structure having a core layer or a coreless circuit structure, which has a plurality of circuit layers 200 such as fan-out redistribution layers. The substrate 20' is made of a dielectric material, such as polybenzoxazole (PBO), polyimide or prepreg. Alternatively, the substrate 20' can be, for example, an organic board, a wafer, or a board with metal wiring.

The circuit layers 200 have a plurality of grounding portions 202 defined therein and a plurality of conductive pads 201 formed on the second side 20b of the substrate 20.

Any desired number of electronic components 21 can be disposed on the substrate 20'. Each of the electronic components 21 can be an active element such as a semiconductor chip, a passive element, such as a resistor, a capacitor or an inductor, or a combination thereof. In an embodiment, the electronic component 21 is an RF chip, such as a Bluetooth chip, a Wi-Fi chip or the like. In an embodiment, the electronic component 21 has a plurality of electrode pads (not shown) electrically connected to the circuit layers 200 through a plurality of bonding wires 210. In another embodiment, the electronic component 21 is disposed on the carrier

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20 in a flip-chip manner and the electrode pads of the electronic component 21 are electrically connected to the circuit layers 200 through a plurality of conductive bumps 210' made of, for example, a solder material. In a further embodiment, the electronic component 21 is directly bonded and electrically connected to the circuit layers 200.

The encapsulant layer 22 has a first surface 22a bonded to the first side 20a of the carrier 20 and a second surface 22b opposite to the first surface 22a. In an embodiment, the encapsulant layer 22 is made of an insulating material, such as polyimide, a dry film, an epoxy resin or a molding compound. The encapsulant layer 22 can be formed on the first side 20a of the carrier 20 by lamination or molding.

Referring to FIG. 2B, a plurality of through holes 230 are formed in the encapsulant layer 22, and extend to the second side 20b of the carrier 20.

In an embodiment, referring to FIG. 2A', the through holes 230 are formed at intersections A of the isolating portions 20''. As such, referring to FIG. 2B', the through holes 230 are positioned at corners of the substrates 20' and have cross-shaped end surfaces 230a.

Referring to FIG. 2C, a metal electroplating process is performed to form a shielding layer 23 on the second surface 22b of the encapsulant layer 22. The shielding layer 23 extends into the through holes 230 to serve as extending portions 23a. The extending portions 23a are in contact and electrical connection with the grounding portions 202 of the carrier 20 so as to serve as electromagnetic shields.

In an embodiment, the shielding layer 23 is made of Au, Ag, Cu, Ni, Fe, Al, or stainless steel (SUS).

The shielding layer 23 can be formed by coating, sputtering, chemical plating, electroless plating or evaporation.

It should be noted that the grounding portions 202 can be formed at any desired position as long as the shielding layer 23 is electrically connected to the grounding portions 202.

Referring to FIGS. 2D and 2D', a singulation process is performed along cutting paths S of FIG. 2C so as to obtain electronic packages 2. The cutting paths S correspond in position to the isolating portions 20'' and pass through the through holes 230. The extending portion 23a extends from a portion of edges (for example, corners) of the second surface 22b of the encapsulant layer 22 to the lateral side 20c of the substrate 20' along the side surface 22c of the encapsulant layer 22, without extending to the second side 20b of the substrate 20', with a portion of the side surface 22c of the encapsulant layer 22 and a portion of the lateral side 20c of the substrate 20' exposed from the shielding layer 23.

In an embodiment, the lateral side 20c of the substrate 20' is adjacent to the first side 20a and the second side 20b, and the side surface 22c of the encapsulant layer 22 is adjacent to the first surface 22a and the second surface 22b.

Further, the grounding portion 202 communicates with the lateral side 20c of the substrate 20' so as to be in contact with the extending portion 23a, and the conductive pads 201 are exposed from the second side 20b of the substrate 20'.

In an embodiment, the extending portion 23a extends from a corner of the second surface 22b of the encapsulant layer 22 toward a corner of the second side 20b of the substrate 20'. The extending portion 23a does not extend to the second side 20b of the substrate 20'. Instead, the extending portion 23a only extends to the intersection of the lateral side 20c and the second side 20b of the substrate 20'.

In addition, in subsequent processes, a plurality of conductive elements (not shown) such as solder balls are

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disposed on the conductive pads **201** for an external device (not shown), such as a package structure or a circuit board to be mounted thereon.

According to the present disclosure, during the formation of the shielding layer **23**, the through holes **230** allow the extending portions **23a** of the shielding layer **23** to extend from a corner of the second surface **22b** of the encapsulant layer **22** toward a corner of the second side **20b** of the substrate **20'**. In an embodiment, the extending portion **23a** only extends to the intersection of the lateral side **20c** and the second side **20b** of the substrate **20'**, without extending to the second side **20b** of the substrate **20'**. As such, the present disclosure prevents the extending portion **23a** from overflowing on the second side **20b** of the substrate **20'** and coming into contact with the conductive pads **201**, thus effectively avoiding a short circuit from occurrence.

Further, the shielding layer **23** that covers an outer periphery of the electronic component **21** protects the electronic component **21** against external EMI during operation of the electronic package **2**, thereby improving electrical performance of the electronic package **2**.

The present disclosure further provides an electronic package **2**, which has: a substrate **20'** having a first side **20a**, a second side **20b** opposite to the first side **20a**, and a lateral side **20c** adjacent to the first side **20a** and the second side **20b**; at least one electronic component **21** disposed on the first side **20a** of the substrate **20'** and electrically connected to the substrate **20'**; an encapsulant layer **22** formed on the first side **20a** of the substrate **20'**, encapsulating the electronic component **21**, and having a first surface **22a** bonded to the first surface **20a** of the substrate **20'**, a second surface **22b** opposite to the first surface **22a**, and a side surface **22c** adjacent to the first surface **22a** and the second surface **22b**; and a shielding layer **23** formed on the second surface **22b** of the encapsulant layer **22** and having an extending portion **23a** extending from a portion of an edge of the second surface **22b** of the encapsulant layer **22** to the lateral side **20c** of the substrate **20'** along the side surface **22c** of the encapsulant layer **22**, without extending to the second side **20b** of the substrate **20'**, with a portion of the side surface **22c** of the encapsulant layer **22** and a portion of the lateral side **20c** of the substrate **20'** exposed from the shielding layer.

In an embodiment, the substrate **20'** has a plurality of conductive pads **201** exposed from the second side **20b** of the substrate **20'**.

In an embodiment, the substrate **20'** has a grounding portion **202** in contact with the shielding layer **23**. In another embodiment, the grounding portion **202** communicates with the lateral side **20c** of the substrate **20'** so as to be in contact with the extending portion **23a** of the shielding layer **23**.

In an embodiment, the encapsulant layer **22** is made of an insulating material.

In an embodiment, the shielding layer **23** is made of a conductive material.

In an embodiment, the extending portion **23a** extends from a corner of the second surface **22b** of the encapsulant layer **22** toward a corner of the second side **20b** of the substrate **20'**.

According to the present disclosure, the extending portion of the shielding layer extends from a portion of an edge of the second surface of the encapsulant layer to the lateral side of the substrate along the side surface of the encapsulant layer, without extending to the second side of the substrate, with a portion of the side surface of the encapsulant layer and a portion of the lateral side of the substrate exposed from the shielding layer. As such, the present disclosure prevents the extending portion from coming into contact with the

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conductive pads of the substrate, thus effectively avoiding a short circuit from occurrence.

The above-described descriptions of the detailed embodiments are only to illustrate the preferred implementation according to the present disclosure, and it is not to limit the scope of the present disclosure. Accordingly, all modifications and variations completed by those with ordinary skill in the art should fall within the scope of present disclosure defined by the appended claims.

What is claimed is:

1. A method for fabricating an electronic package, comprising:

providing a substrate having a grounding circuit line, a first side, a second side opposite to the first side, and a lateral side adjacent to the first side and the second side; disposing an electronic component on the first side of the substrate, and electrically connecting the electronic component to the substrate;

forming on the substrate an encapsulant layer encapsulating the electronic component and having a first surface bonded to the first side of the substrate, a second surface opposite to the first surface, and a side surface adjacent to the first surface and the second surface; and

forming on the side surface of the encapsulant layer a shielding layer having an extending portion extending from a portion of an edge of the side surface of the encapsulant layer to the lateral side of the substrate along the side surface of the encapsulant layer, the extending portion being free from extending to the second side of the substrate, with a portion of the lateral side of the substrate exposed from the shielding layer, wherein the grounding circuit line is in contact with the shielding layer, and the grounding circuit line communicates with the lateral side of the substrate and is in contact with the extending portion of the shielding layer,

wherein the extending portion extends from a corner of the second surface of the encapsulant layer toward a corner of the second side of the substrate.

2. The method of claim 1, wherein the substrate has a plurality of conductive pads exposed from the second side of the substrate.

3. The method of claim 1, wherein the shielding layer is formed on the second surface of the encapsulant layer.

4. The method of claim 1, wherein a portion of the side surface of the encapsulant layer is exposed from the shielding layer.

5. The method of claim 1, wherein the encapsulant layer is made of an insulating material.

6. The method of claim 1, wherein the shielding layer is made of a conductive material.

7. A method of forming the shielding layer according to claim 1, comprising:

providing a carrier having a plurality of substrates and a plurality of isolating portions formed between the substrates;

disposing a plurality of electronic components on the substrates, with an encapsulant layer encapsulating the electronic components, the encapsulant layer having a first surface bonded to the first side of the substrates, a second surface opposite to the first surface, and a side surface adjacent to the first surface and the second surface;

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forming in the encapsulant layer a plurality of through holes extending to lateral surfaces of the substrates and corresponding in position to the isolating portions at corners of the substrates;

forming the shielding layer on the second surface of the encapsulant layer, with the shielding layer extending in the through holes to form extending portions; and performing a singulation process along the isolating portions to separate the substrates from one another.

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